

# MC74LVX50

## Hex Buffer

The MC74LVX50 is an advanced high speed CMOS buffer fabricated with silicon gate CMOS technology.

The internal circuit is composed of three stages, including a buffered output which provides high noise immunity and stable output. The inputs tolerate voltages up to 7.0 V, allowing the interface of 5.0 V systems to 3.0 V systems.

### Features

- High Speed:  $t_{PD} = 4.1 \text{ ns}$  (Typ) at  $V_{CC} = 3.3 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 2 \mu\text{A}$  (Max) at  $T_A = 25^\circ\text{C}$
- High Noise Immunity:  $V_{NIH} = V_{NIL} = 28\% V_{CC}$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Designed for 2.0 V to 3.6 V Operating Range
- Low Noise:  $V_{OLP} = 0.5 \text{ V}$  (Max)
- These Devices are Pb-Free and are RoHS Compliant

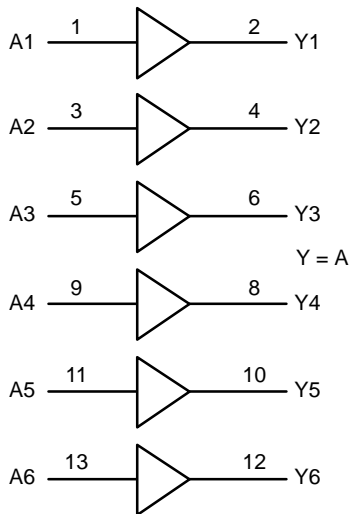


Figure 1. Logic Diagram

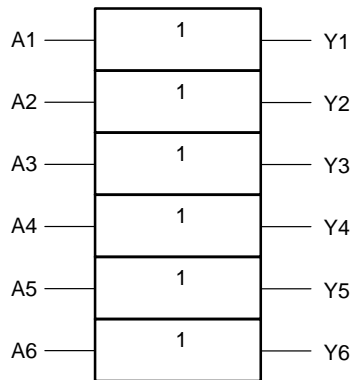


Figure 2. Logic Symbol

### FUNCTION TABLE

| A Input | Y Output |
|---------|----------|
| L       | L        |
| H       | H        |



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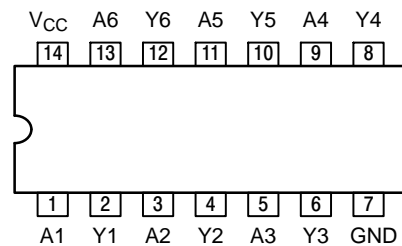


SOIC-14 NB  
D SUFFIX  
CASE 751A



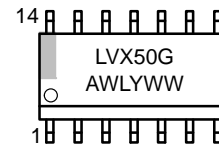
TSSOP-14  
DT SUFFIX  
CASE 948G

### PIN ASSIGNMENT

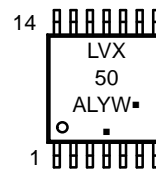


14-Lead (Top View)

### MARKING DIAGRAMS



SOIC-14 NB



TSSOP-14

LVX50 = Specific Device Code  
A = Assembly Location  
WL, L = Wafer Lot  
Y = Year  
WW, W = Work Week  
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

# MC74LVX50

## MAXIMUM RATINGS

| Symbol               | Parameter   | Value                         | Unit |
|----------------------|---|-------------------------------|------|
| V <sub>CC</sub>      | DC Supply Voltage   | -0.5 to +7.0                  | V    |
| V <sub>IN</sub>      | DC Input Voltage  | -0.5 to +7.0                  | V    |
| V <sub>OUT</sub>     | DC Output Voltage   | -0.5 to V <sub>CC</sub> + 0.5 | V    |
| I <sub>IK</sub>      | DC Input Diode Current<br>V <sub>I</sub> < GND  | -20                           | mA   |
| I <sub>OK</sub>      | DC Output Diode Current<br>V <sub>O</sub> < GND   | ±20                           | mA   |
| I <sub>OUT</sub>     | DC Output Sink Current  | ±25                           | mA   |
| I <sub>CC</sub>      | DC Supply Current per Supply Pin  | ±50                           | mA   |
| T <sub>STG</sub>     | Storage Temperature Range   | -65 to +150                   | °C   |
| T <sub>L</sub>       | Lead Temperature, 1 mm from Case for 10 Seconds   | 260                           | °C   |
| T <sub>J</sub>       | Junction Temperature under Bias   | +150                          | °C   |
| θ <sub>JA</sub>      | Thermal Resistance<br>(Note 1)<br>SOIC<br>TSSOP   | 125<br>170                    | °C/W |
| MSL                  | Moisture Sensitivity  | Level 1                       |      |
| F <sub>R</sub>       | Flammability Rating<br>Oxygen Index: 30% – 35%  | UL 94-V0 @ 0.125 in           |      |
| V <sub>ESD</sub>     | ESD Withstand Voltage<br>Human Body Model (Note 2)<br>Machine Model (Note 3)<br>Charged Device Model (Note 4) | > 2000<br>> 200<br>2000       | V    |
| I <sub>Latchup</sub> | Latchup Performance<br>Above V <sub>CC</sub> and Below GND at 85°C (Note 5)                                   | ±300                          | mA   |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/JESD22-A115-A.
4. Tested to JESD22-C101-A.
5. Tested to EIA/JESD78.

## RECOMMENDED OPERATING CONDITIONS

| Symbol          | Parameter  | Min | Max             | Unit |
|-----------------|--|-----|-----------------|------|
| V <sub>CC</sub> | Supply Voltage   | 2.0 | 3.6             | V    |
| V <sub>I</sub>  | Input Voltage<br>(Note 6)  | 0   | 5.5             | V    |
| V <sub>O</sub>  | Output Voltage<br>(HIGH or LOW State)                                | 0   | V <sub>CC</sub> | V    |
| T <sub>A</sub>  | Operating Free-Air Temperature                                       | -40 | +85             | °C   |
| Δt/ΔV           | Input Transition Rise or Fall Rate<br>V <sub>CC</sub> = 3.0 V ±0.3 V | 0   | 100             | ns/V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

6. Unused inputs may not be left open. All inputs must be tied to a high- or low-logic input voltage level.

NOTE: The θ<sub>JA</sub> of the package is equal to 1/Derating. Higher junction temperatures may affect the expected lifetime of the device per the table and figure below.

# MC74LVX50

## DC ELECTRICAL CHARACTERISTICS

| Symbol          | Parameter  | Test Conditions   | V <sub>CC</sub> (V) | T <sub>A</sub> = 25°C |            |                    | T <sub>A</sub> ≤ 85°C |                    | Unit |
|-----------------|--|---|---------------------|-----------------------|------------|--------------------|-----------------------|--------------------|------|
|                 |  |   |                     | Min                   | Typ        | Max                | Min                   | Max                |      |
| V <sub>IH</sub> | High-Level Input Voltage   |   | 2.0<br>3.0<br>3.6   | 1.5<br>2.0<br>2.4     |            |                    | 1.5<br>2.0<br>2.4     |                    | V    |
| V <sub>IL</sub> | Low-Level Input Voltage  |   | 2.0<br>3.0<br>3.6   |                       |            | 0.5<br>0.8<br>0.8  |                       | 0.5<br>0.8<br>0.8  | V    |
| V <sub>OH</sub> | High-Level Output Voltage<br>(V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> ) | I <sub>OH</sub> = -50 μA<br>I <sub>OH</sub> = -50 μA<br>I <sub>OH</sub> = -4 mA | 2.0<br>3.0<br>3.0   | 1.9<br>2.9<br>2.58    | 2.0<br>3.0 |                    | 1.9<br>2.9<br>2.48    |                    | V    |
| V <sub>OL</sub> | Low-Level Output Voltage<br>(V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> )  | I <sub>OL</sub> = 50 μA<br>I <sub>OL</sub> = 50 μA<br>I <sub>OL</sub> = 4 mA    | 2.0<br>3.0<br>3.0   |                       | 0.0<br>0.0 | 0.1<br>0.1<br>0.36 |                       | 0.1<br>0.1<br>0.44 | V    |
| I <sub>IN</sub> | Input Leakage Current  | V <sub>IN</sub> = 5.5 V or GND  | 0 to<br>3.6         |                       |            | ±0.1               |                       | ±1.0               | μA   |
| I <sub>CC</sub> | Quiescent Supply Current   | V <sub>IN</sub> = V <sub>CC</sub> or GND  | 3.6                 |                       |            | 2.0                |                       | 20.0               | μA   |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## AC ELECTRICAL CHARACTERISTICS Input t<sub>r</sub> = t<sub>f</sub> = 3.0 ns

| Symbol                                   | Parameter                              | Test Conditions   | T <sub>A</sub> = 25°C                   |            |              | T <sub>A</sub> ≤ 85°C |              | Unit |
|--|--|---|---|------------|--------------|-----------------------|--------------|------|
|  |  |   | Min                                     | Typ        | Max          | Min                   | Max          |      |
| t <sub>PLH</sub> ,<br>t <sub>PHL</sub>   | Propagation Delay,<br>Input A to Y     | V <sub>CC</sub> = 2.7 V    C <sub>L</sub> = 15 pF<br>C <sub>L</sub> = 50 pF         |   | 5.4<br>7.9 | 10.1<br>13.6 | 1.0<br>1.0            | 12.5<br>16.0 | ns   |
|  |  | V <sub>CC</sub> = 3.3 V ± 0.3 V    C <sub>L</sub> = 15 pF<br>C <sub>L</sub> = 50 pF |   | 4.1<br>6.6 | 6.2<br>9.7   | 1.0<br>1.0            | 7.5<br>11.5  |      |
| t <sub>OSSL</sub> ,<br>t <sub>OSLH</sub> | Output-to-Output Skew<br>(Note 7)      | V <sub>CC</sub> = 2.7 V    C <sub>L</sub> = 50 pF                                   |   |            | 1.5          |                       | 1.5          | ns   |
|  |  | V <sub>CC</sub> = 3.3 V ± 0.3V    C <sub>L</sub> = 50 pF                            |   |            | 1.5          |                       | 1.5          |      |
| C <sub>IN</sub>                          | Input Capacitance                      |   |   | 4          | 10           |                       | 10           | pF   |
| C <sub>PD</sub>                          | Power Dissipation Capacitance (Note 8) |   | Typical @ 25°C, V <sub>CC</sub> = 3.3 V |            |              |                       | 15           | pF   |

7. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSSL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

8. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no-load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

## NOISE CHARACTERISTICS Input t<sub>r</sub> = t<sub>f</sub> = 3.0ns, C<sub>L</sub> = 50pF, V<sub>CC</sub> = 3.3 V

| Symbol           | Characteristic                               | T <sub>A</sub> = 25°C |      | Unit |
|------------------|--|-----------------------|------|------|
|                  |  | Typ                   | Max  |      |
| V <sub>OLP</sub> | Quiet Output Maximum Dynamic V <sub>OL</sub> | 0.3                   | 0.5  | V    |
| V <sub>OLV</sub> | Quiet Output Minimum Dynamic V <sub>OL</sub> | -0.3                  | -0.5 | V    |
| V <sub>IHD</sub> | Minimum High Level Dynamic Input Voltage     |                       | 2.0  | V    |
| V <sub>ILD</sub> | Maximum Low Level Dynamic Input Voltage      |                       | 0.8  | V    |

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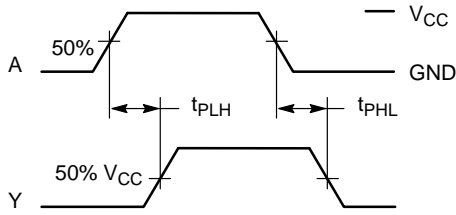
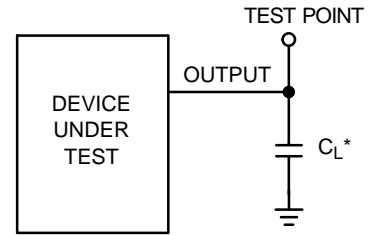


Figure 3. Switching Waveforms



\*Includes all probe and jig capacitance

Figure 4. Test Circuit

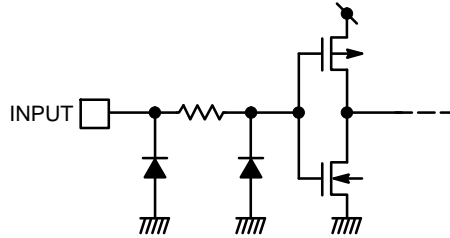


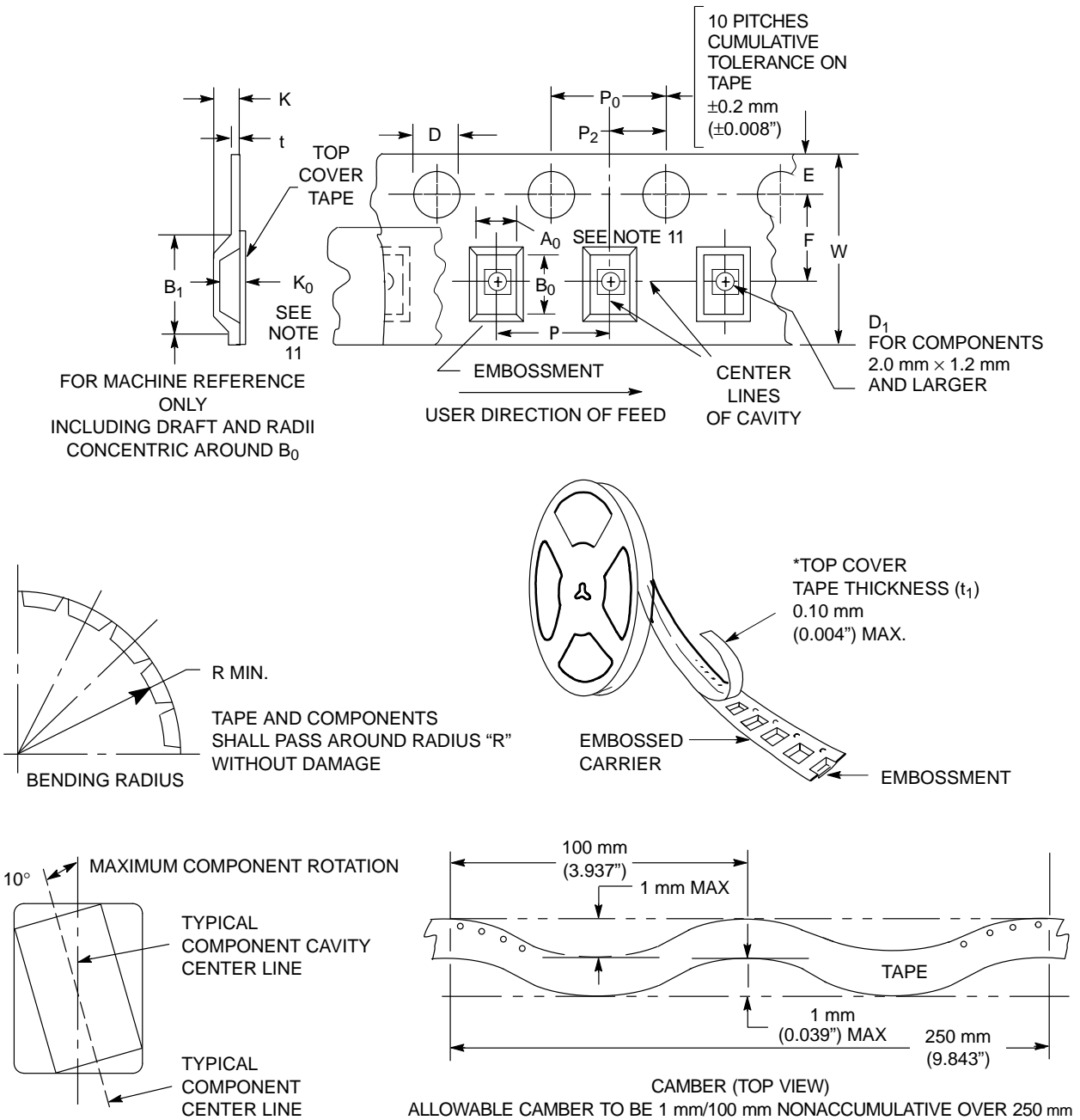
Figure 5. Input Equivalent Circuit

## EMBOSSED CARRIER DIMENSIONS (See Notes 9 and 10)

| Tape Size | B <sub>1</sub> Max  | D                                   | D <sub>1</sub>            | E                                     | F                                      | K                          | P  | P <sub>0</sub>                       | P <sub>2</sub>                       | R                | T                 | W                                     |
|-----------|---------------------|-------------------------------------|---------------------------|---------------------------------------|--|----------------------------|--|--------------------------------------|--------------------------------------|------------------|-------------------|---------------------------------------|
| 8 mm      | 4.35 mm<br>(0.179") | 1.5 mm<br>+ 0.1<br>-0.0<br>(0.059") | 1.0 mm<br>Min<br>(0.179") | 1.75 mm<br>±0.1<br>(0.069<br>±0.004") | 3.5 mm<br>±0.5<br>(1.38<br>±0.002")    | 2.4 mm<br>Max<br>(0.094")  | 4.0 mm<br>±0.10<br>(0.157<br>±0.004")  | 4.0 mm<br>±0.1<br>(0.157<br>±0.004") | 2.0 mm<br>±0.1<br>(0.079<br>±0.004") | 25 mm<br>(0.98") | 0.6 mm<br>(0.024) | 8.3 mm<br>(0.327)                     |
| 12 mm     | 8.2 mm<br>(0.323")  | +0.004<br>-0.0)                     | 1.5 mm<br>Min<br>(0.060)  |                                       | 5.5 mm<br>±0.5<br>(0.217<br>±0.002")   | 6.4 mm<br>Max<br>(0.252")  | 4.0 mm<br>±0.10<br>(0.157<br>±0.004")<br>8.0 mm<br>±0.10<br>(0.315<br>±0.004")   |                                      |                                      | 30 mm<br>(1.18") |                   | 12.0 mm<br>±0.3<br>(0.470<br>±0.012") |
| 16 mm     | 12.1 mm<br>(0.476") |                                     |                           |                                       | 7.5 mm<br>±0.10<br>(0.295<br>±0.004")  | 7.9 mm<br>Max<br>(0.311")  | 4.0 mm<br>±0.10<br>(0.157<br>±0.004")<br>8.0 mm<br>±0.10<br>(0.315<br>±0.004")<br>12.0 mm<br>±0.10<br>(0.472<br>±0.004") |                                      |                                      |                  |                   | 16.3 mm<br>(0.642)                    |
| 24 mm     | 20.1 mm<br>(0.791") |                                     |                           |                                       | 11.5 mm<br>±0.10<br>(0.453<br>±0.004") | 11.9 mm<br>Max<br>(0.468") | 16.0 mm<br>±0.10<br>(0.63<br>±0.004")  |                                      |                                      |                  |                   | 24.3 mm<br>(0.957)                    |

9. Metric Dimensions Govern—English are in parentheses for reference only.

10. A<sub>0</sub>, B<sub>0</sub>, and K<sub>0</sub> are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity



11.  $A_0$ ,  $B_0$ , and  $K_0$  are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity

Figure 6. Carrier Tape Specifications

# MC74LVX50

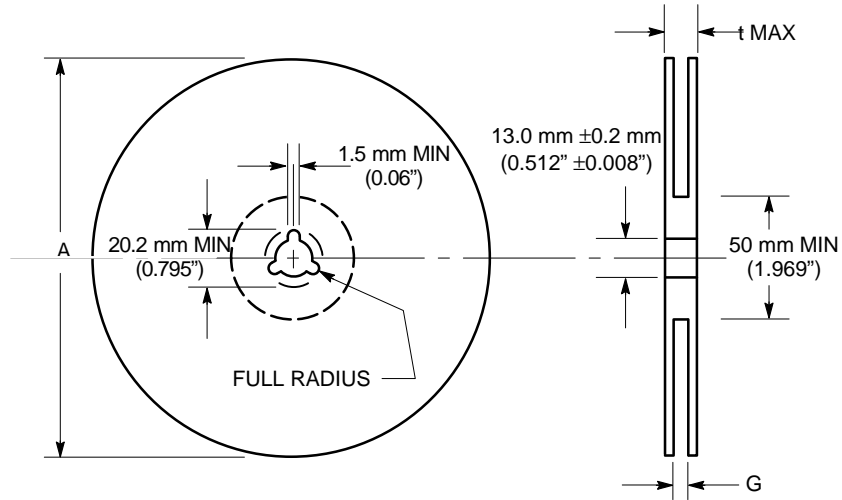


Figure 7. Reel Dimensions

## REEL DIMENSIONS

| Tape Size | T&R Suffix | A Max               | G  | t Max               |
|-----------|------------|---------------------|--|---------------------|
| 8 mm      | T1, T2     | 178 mm<br>(7")      | 8.4 mm, +1.5 mm, -0.0<br>(0.33" + 0.059", -0.00)   | 14.4 mm<br>(0.56")  |
| 8 mm      | T3, T4     | 330 mm<br>(13")     | 8.4 mm, +1.5 mm, -0.0<br>(0.33" + 0.059", -0.00)   | 14.4 mm<br>(0.56")  |
| 12 mm     | R2         | 330 mm<br>(13")     | 12.4 mm, +2.0 mm, -0.0<br>(0.49" + 0.079", -0.00)  | 18.4 mm<br>(0.72")  |
| 16 mm     | R2         | 360 mm<br>(14.173") | 16.4 mm, +2.0 mm, -0.0<br>(0.646" + 0.078", -0.00) | 22.4 mm<br>(0.882") |
| 24 mm     | R2         | 360 mm<br>(14.173") | 24.4 mm, +2.0 mm, -0.0<br>(0.961" + 0.078", -0.00) | 30.4 mm<br>(1.197") |

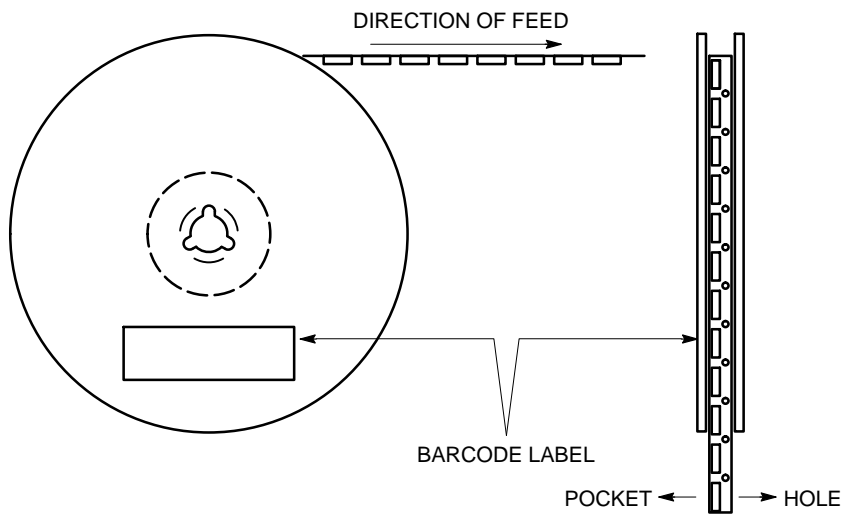
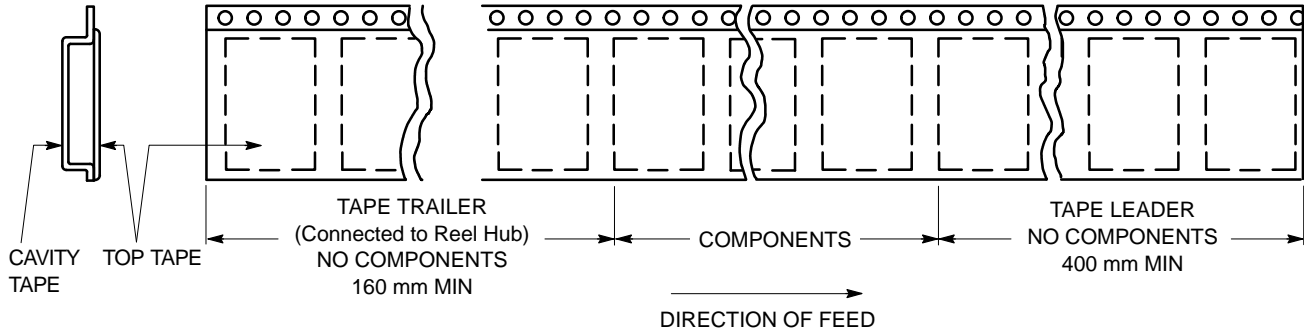
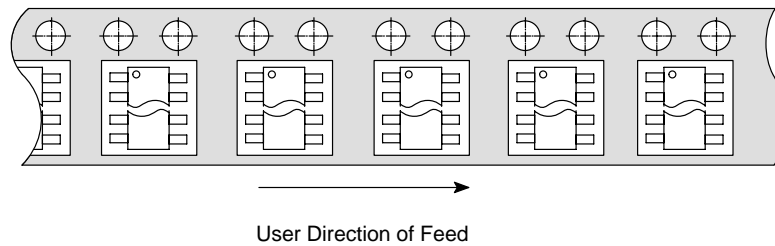


Figure 8. Reel Winding Direction

# MC74LVX50



**Figure 9. Tape Ends for Finished Goods**



**Figure 10. TSSOP and SOIC R2 Reel Configuration/Orientation**

## TAPE UTILIZATION BY PACKAGE

| Tape Size | SOIC                   | TSSOP            | QFN              | SC88A / SOT-353<br>SC88/SOT-363 |
|-----------|------------------------|------------------|------------------|---------------------------------|
| 8 mm      |                        |                  |                  | 5-, 6-Lead                      |
| 12 mm     | 8-Lead                 | 8-, 14-, 16-Lead | 8-, 14-, 16-Lead |                                 |
| 16 mm     | 14-, 16-Lead           | 20-, 24-Lead     | 20-, 24-Lead     |                                 |
| 24 mm     | 18-, 20-, 24-, 28-Lead | 48-, 56-Lead     | 48-, 56-Lead     |                                 |

## ORDERING INFORMATION

| Device         | Package                 | Shipping <sup>†</sup> |
|----------------|-------------------------|-----------------------|
| MC74LVX50DG    | SOIC-14 NB<br>(Pb-Free) | 55 Units / Rail       |
| MC74LVX50DR2G  | SOIC-14 NB<br>(Pb-Free) | 2500 Tape & Reel      |
| MC74LVX50DTG   | TSSOP-14<br>(Pb-Free)   | 96 Units / Rail       |
| MC74LVX50DTR2G | TSSOP-14<br>(Pb-Free)   | 2500 Tape & Reel      |

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-14 NB  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
  5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

| DIM | MILLIMETERS |      | INCHES    |       |
|-----|-------------|------|-----------|-------|
|     | MIN         | MAX  | MIN       | MAX   |
| A   | 1.35        | 1.75 | 0.054     | 0.068 |
| A1  | 0.10        | 0.25 | 0.004     | 0.010 |
| A3  | 0.19        | 0.25 | 0.008     | 0.010 |
| b   | 0.35        | 0.49 | 0.014     | 0.019 |
| D   | 8.55        | 8.75 | 0.337     | 0.344 |
| E   | 3.80        | 4.00 | 0.150     | 0.157 |
| e   | 1.27 BSC    |      | 0.050 BSC |       |
| H   | 5.80        | 6.20 | 0.228     | 0.244 |
| h   | 0.25        | 0.50 | 0.010     | 0.019 |
| L   | 0.40        | 1.25 | 0.016     | 0.049 |
| M   | 0°          | 7°   | 0°        | 7°    |

### SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### GENERIC MARKING DIAGRAM\*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

|                  |             |  |
|------------------|-------------|--|
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**SOIC-14**  
**CASE 751A-03**  
**ISSUE L**

DATE 03 FEB 2016

STYLE 1:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. ANODE/CATHODE  
 8. ANODE/CATHODE  
 9. ANODE/CATHODE  
 10. NO CONNECTION  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 2:  
 CANCELLED

STYLE 3:  
 PIN 1. NO CONNECTION  
 2. ANODE  
 3. ANODE  
 4. NO CONNECTION  
 5. ANODE  
 6. NO CONNECTION  
 7. ANODE  
 8. ANODE  
 9. ANODE  
 10. NO CONNECTION  
 11. ANODE  
 12. ANODE  
 13. NO CONNECTION  
 14. COMMON CATHODE

STYLE 4:  
 PIN 1. NO CONNECTION  
 2. CATHODE  
 3. CATHODE  
 4. NO CONNECTION  
 5. CATHODE  
 6. NO CONNECTION  
 7. CATHODE  
 8. CATHODE  
 9. CATHODE  
 10. NO CONNECTION  
 11. CATHODE  
 12. CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 5:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. COMMON ANODE  
 8. COMMON CATHODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 6:  
 PIN 1. CATHODE  
 2. CATHODE  
 3. CATHODE  
 4. CATHODE  
 5. CATHODE  
 6. CATHODE  
 7. CATHODE  
 8. ANODE  
 9. ANODE  
 10. ANODE  
 11. ANODE  
 12. ANODE  
 13. ANODE  
 14. ANODE

STYLE 7:  
 PIN 1. ANODE/CATHODE  
 2. COMMON ANODE  
 3. COMMON CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
 7. ANODE/CATHODE  
 8. ANODE/CATHODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. COMMON CATHODE  
 12. COMMON ANODE  
 13. ANODE/CATHODE  
 14. ANODE/CATHODE

STYLE 8:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
 7. COMMON ANODE  
 8. COMMON ANODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. NO CONNECTION  
 12. ANODE/CATHODE  
 13. ANODE/CATHODE  
 14. COMMON CATHODE

|                         |                    |   |
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| <b>DESCRIPTION:</b>     | <b>SOIC-14 NB</b>  | <b>PAGE 2 OF 2</b>  |

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



**TSSOP-14 WB**  
CASE 948G  
ISSUE C

DATE 17 FEB 2016

SCALE 2:1



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS |      | INCHES    |       |
|-----|-------------|------|-----------|-------|
|     | MIN         | MAX  | MIN       | MAX   |
| A   | 4.90        | 5.10 | 0.193     | 0.200 |
| B   | 4.30        | 4.50 | 0.169     | 0.177 |
| C   | ---         | 1.20 | ---       | 0.047 |
| D   | 0.05        | 0.15 | 0.002     | 0.006 |
| F   | 0.50        | 0.75 | 0.020     | 0.030 |
| G   | 0.65 BSC    |      | 0.026 BSC |       |
| H   | 0.50        | 0.60 | 0.020     | 0.024 |
| J   | 0.09        | 0.20 | 0.004     | 0.008 |
| J1  | 0.09        | 0.16 | 0.004     | 0.006 |
| K   | 0.19        | 0.30 | 0.007     | 0.012 |
| K1  | 0.19        | 0.25 | 0.007     | 0.010 |
| L   | 6.40 BSC    |      | 0.252 BSC |       |
| M   | 0°          | 8°   | 0°        | 8°    |

**GENERIC MARKING DIAGRAM\***

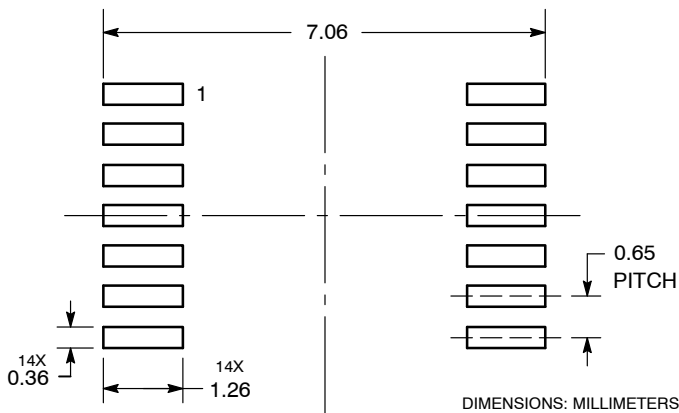


- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

**SOLDERING FOOTPRINT**



|                         |                    |  |
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